The

| Notice of Allowability | Application No. | Applicant(s) | |
|---|------------------------------------|----------------------------------|-------|
| | 10/771,593 | YILMAZ, HAMZA | |
| | Examiner | Art Unit | |
| | Fetsum Abraham | 2826 | |
| The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308. | | | |
| 1. This communication is responsive to | | | |
| 2. The allowed claim(s) is/are <u>1-8 and 38</u> . | | | |
| 3. Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some* c) None of the: Certified copies of the priority documents have been received. Certified copies of the priority documents have been received in Application No. Copies of the certified copies of the priority documents have been received in this national stage application from the International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application. THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. | | | |
| 4. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient. | | | |
| 5. CORRECTED DRAWINGS (as "replacement sheets") must be submitted. | | | |
| (a) Including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached | | | |
| 1) hereto or 2) to Paper No./Mail Date | | | |
| (b) ☐ including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date | | | |
| Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d). | | | |
| DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL. | | | |
| Attachment(s) 1. ☐ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date | | (PTO-413), le nent/Comment | ŕ |
| 4. Examiner's Comment Regarding Requirement for Deposit of Biological Material . | 8. ⊠ Examiner's Stateme 9. □ Other | nt of Reasons for Allo | wance |

EXAMINER'S AMENDMENT

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Mr. David E. Steuber on 11/4/05.

The application has been amended as follows:

The expression "laterally" has been added between "sidewalls" and "separating" in line 6 of claim 1.

Statement of reasons for allowance

Claims 1-8,38 are allowed.

The claimed structure conforming to JFET device having field shield region of second conductivity type laterally provided with sidewall insulation layers to laterally separate from the first conductivity type substrate while forming a PN junction at the lower surface with the semiconductor substrate, the structure provided with upper, lower and shield electrodes and the overall motivation and specifically the underlined statement for forming the field shield layer as taught in the specification as follows is not taught or rendered obvious by the prior arts.

[0038] P-shield regions 320 can be formed by a selective epitaxial deposition after the RIE etch of the silicon and after the formation of a sidewall oxide. The basic structure shown in FIG. 2B is applied to a trench MOSFET (N+ substrate) and also

Art Unit: 2826

IGBT (P+ substrate) structure in FIG. 2A to improve the blocking capability with thin gate oxide. The structure shown in FIG. 2B can be applied to make a low barrier height diode such as the Schottky barrier diode, as shown in FIG. 2C, or the vertical JFET structure, as shown in FIG. 2D. The devices shown in FIGS. 2A-2D share the novel field shield structure, which is a P-region bounded by dielectricwalls on the sides and a PN junction below. The dielectric sidewalls prevent the spread of the P region expansion laterally by blocking the lateral diffusion of acceptors (e.g., boron) during device processing at high temperatures (e.g., above 800.degree. C.). Of course, the polarities may be reversed in which case the field shield region would be formed of N-type material.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Fetsum Abraham whose telephone number is: 571-272-1911. The examiner can normally be reached on 8:00 - 18:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan J Flynn can be reached on 571-272-1915.

Fetsum Abraham